

SID

Factory: Rot am See

Article:

ML2

Provided:

Customer:

Date:

28.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: Lamination (not SD-relevant)

Material Text	Mat. Nr.	µm	Stackup	Process overview
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C-RS Pyralux AP8525E 305x457mm 0.050mm...	50200050	18	VS		A01	B00
		50				
		18				
A-RS Klebefolie 3M 9460 50µm	50200608	50	RS		A02	
A-RS-FR4-ML-0.152mm-018+018-TG150-HF-...	50203026	152			A02	

Thickness after Pressing

B00:

270 µm

Tol+:

50 µm

Tol-:

50 µm

Dmax:

320 µm

Dmin:

220 µm

Thickness over all

425 µm

Tol+:

75 µm

Tol-:

75 µm

Dmax:

500 µm

Dmin:

350 µm

Demand for customer

Thickness (D):

300 µm

Tol+:

50 µm

Tol-:

50 µm

Dmax:

350 µm

Dmin:

250 µm

Measuring point:

(15) thickness after pressing

nominal:

288 µm

Version 1.2.20.35

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